Material Composition Declaration

This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard
http://www.ipc.org/IPC-175x

Form Type*
Distribute

Declaration Class*
Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Infomation

Supplier Information

Company Name * **Fairchild Semiconductor**	Company Unique ID 00-489-5751	Unique ID Authority Dun & Bradstreet	**Response Date*** **Sat, Feb 22, 2014 03:41 AM**
Contact Name * **David Lancaster**	Title - Contact Product Ecology	**Phone - Contact *** **801-562-7455**	**Email - Contact *** **david.lancaster@fairchildsemi.com**
Authorized Representative * **David Lancaster**	Title - Representative Product Ecology	**Phone - Representative *** **801-562-7455**	Email - Representative * david.lancaster@fairchildsemi.com

Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	**Weight***	UOM	Unit Type
MM74HCT573WMX	MM74HCT573WMX	SOIC-20W			INTERNAL PENANG	**0.532373**	g	Each

Manufacturing Process Information

Terminal Finish	Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	No Reflow cycles
Matte Tin (Sn)	CU Alloy	1	260 C	30 seconds	3

* Required Field

RoHS Material Composition Declaration	**Declaration Type * Custom**

RoHS Directive 2011/65/EU	**RoHS Definition:** Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

This document is Fairchild Semiconductor’s statement regarding the directive 2011/65/EU of the European Parliament and of the council of 8 June 2011on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Recast). The content of this document is based upon information collected from Fairchild Semiconductor supply chain, manufacturing facilities and affiliates worldwide.

The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU. Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild’s products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild’s standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.

Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification. This statement may not include information regarding the miniscule quantities of dopant and metal materials in the electrical devices contained within the finished product. CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.

RoHS Declaration *	**1 - Item(s) does not contain RoHS restricted substances per the definition above**	**Supplier Acceptance * Accepted**

Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version EL-2011/534/EU
None

Declaration Signature

Supplier Signature	David Lancaster DAVID LANCASTER - PRODUCT ECOLOGY MANAGER

Homogeneous Material Composition Declaration for Electronic Products

Item/SubItem Name SOIC-20W

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Chip	Other inorganic materials	6.990	Supplier		Silicon	6.990	7440-21-3	13130
Die Attach	Other Organic Materials	0.707	Supplier		Acrylic Resin	0.152	54208-63-8	286
			Supplier		Silver	0.555	7440-22-4	1043
Encapsulation	Thermoplastics	414.560	B	Antimony/Antimony Compounds	Antimony Trioxide	8.300	1309-64-4	15591
			B	Brominated Flame Retardants (other than PBCs or PBDEs)	Bromine Resin	4.150	6386-73-8	7795
			Supplier		Carbon Black	3.110	1333-86-4	5842
			Supplier		Epoxy Resin	120.000	29690-82-2	225406
			Supplier		Silica, vitreous	279.000	60676-86-0	524068
Lead Frame	Copper & its alloys	105.720	Supplier		Copper	103.000	7440-50-8	193473
			Supplier		Iron	2.540	7439-89-6	4771
			Supplier		Phosphorus	0.042	7723-14-0	80
			Supplier		Zinc	0.138	7440-66-6	259
Plating	Other Nonferrous metals & alloys	3.900	Supplier		Tin	3.900	7440-31-5	7326
Wire Bond	Precious metals	0.496	Supplier		Gold	0.496	7440-57-5	932